

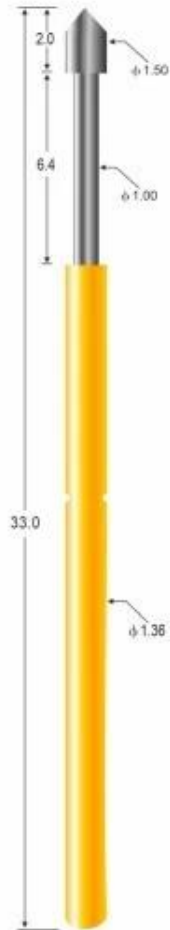


SFENG 1984 PCB



Model	SF-P100
Thickness	1.90mm [0.0748"]
Surface Finish	Immersion: 1.35mm [0.0532"] Electroless: 1.40mm [0.0551"]
Width	6.3 [0.2481"]
Length	120
Material	Be Cu, Rh Electroless Immersion
Current	3A
Temperature	50
Pressure	100
Weight	7



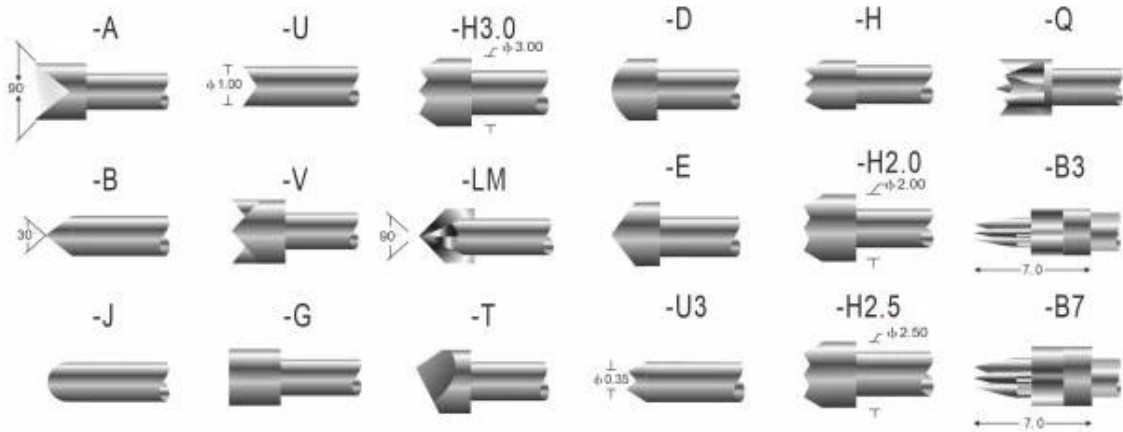


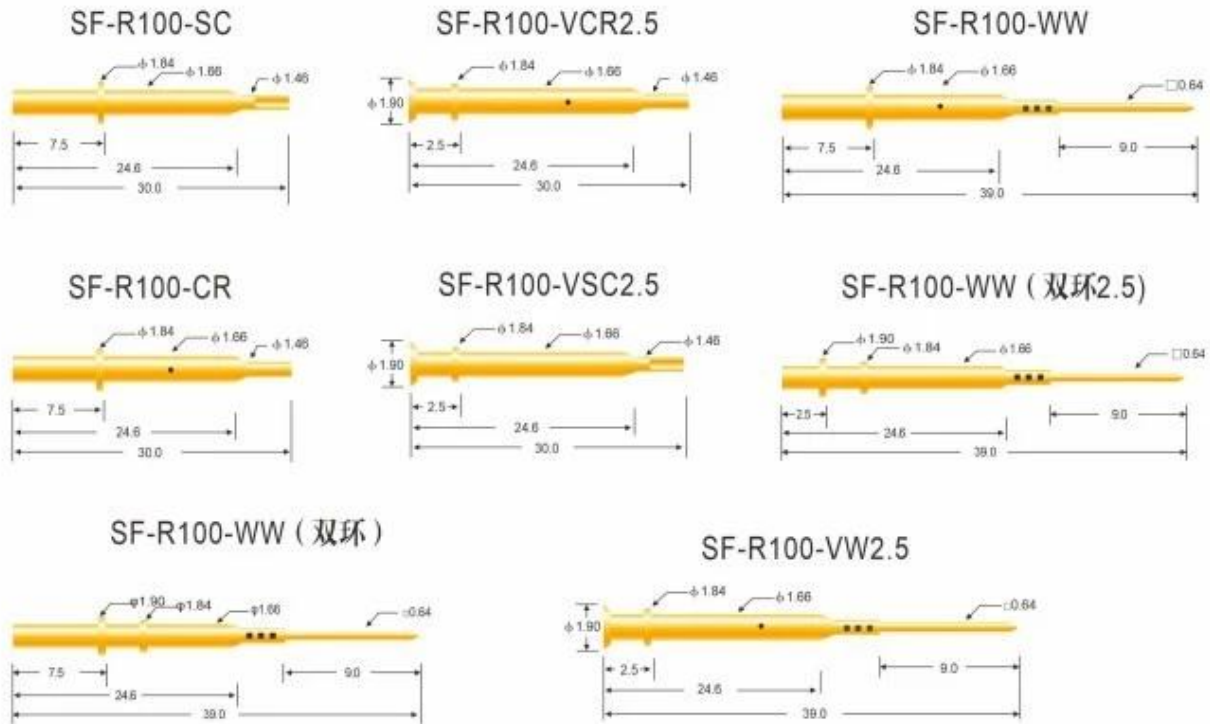
SF-P100-E

技术规格 PROBE SPECIFICATIONS

Recommended minimum center 最小间距	1.90mm(.0748 ")
Mounting hole size 钻孔尺寸	压克力: 1.35mm(.0532 ") 电木板、玻璃纤维板: 1.40mm(.0551 ")
Full travel 行程	6.3(.2481 ")
Spring force 弹簧压力	120g(克)
Materials and finishes 材料及涂饰	Plunger:SK4, Ni or Au plated BeCu, Ni or Au plated Phosphor bronze, Ni or Au plated Barrel:Phosphor bronze, Au plated Spring:Stainless steel
Current rating 额定电流	3A(安培)
Contact resistance 接触电阻	50mΩ(毫欧姆)

Receptacle specifications
Materials and finishes: Phosphor bronze,Gold plated





技术规格 PROBE SPECIFICATIONS

Recommended minimum center 最小间距	2.54mm(.1000 ")
Mounting hole size 钻孔尺寸	压克力: 1.70mm(.0670 ") 电木板、玻璃纤维板: 1.75mm(.0689 ")
Materials and finishes 材料及涂饰	Barrel: Brass, Gold plated
Connections 接线形式	Crimp: R100-VCR2.5, R100-CR Solder cup: R100-VSC2.5, R100-SC Wire wrap: R100-VW2.5, R100-WW, R100-WW(双环2.5), R100-WW(双环)

Receptacle specifications
Materials and finishes: Phosphor bronze, Gold plated



1. 24
2. OEM
- 3.
- 4.



1. PCB ICT FCT
2. Pogo pin
3. BGA
4. QZ VZ LM
- 5.
6. /
7. 30#OK POM



1. Raw material warehouse



2. Lathe workshop



3. Assemble workshop



4. Quality inspection



5. Finished products



6. Packing





Q1.□□□□□□

A1: □□□□□□□□□□□□□□□□□□□□

Q2.□□□□□□

A2: □□□□□□□□□□□□□□□□□□□□□□□□□□□□

Q3.□□□□□

A3: □□□□□□□□□□□□□□□□□□□

Q4.□□□□□

A4: □□□□□□□□□□□□□□□□□□□□□□□□□□

Q5.□□□□□□□□□□

A5: [Placeholder]

Q6. [Placeholder]

A6: [Placeholder]

Q7. [Placeholder] **OEM** [Placeholder] **ODM** [Placeholder]

A7: [Placeholder] OEM/ODM [Placeholder]

Q8. [Placeholder]

A8: [Placeholder]